Place 0.1μF as close to the VCC as possible. Also ensure sufficient metal for Vcc and Gnd for ESD conduction.
MSP430F5528 COMMUNICATIONS HID-BRIDGE

USB_LDO
USB_GND
USB_GND
USB_GND
USB_GND
C202, C203, C204
near pin 11, 15, 40

HUB_DM1
HUB_DP1
HUB_DP
HUB_DM

HID-BRIDGE TXIN
HID-BRIDGE TXOUT
HID-BRIDGE RXIN
HID-BRIDGE RXOUT
HID-BRIDGE SCL
HID-BRIDGE SDA
HID-BRIDGE VUSB
HID-BRIDGE V18
HID-BRIDGE VCORE
HID-BRIDGE V18

HID-BRIDGE LED5
HID-BRIDGE LED4
HID-BRIDGE LED3
HID-BRIDGE LED2
HID-BRIDGE LED1
HID-BRIDGE LED0

POHUB0DP1
POHUB0RXD
POHUB0TXD
POHUB0SCL
POHUB0SDA
POHID0BRIDGE0RXD
POHID0BRIDGE0TXD
POHID0BRIDGE0SCL
POHID0BRIDGE0SDA

54 MHz
22pF
C200
HID-BRIDGE_XT2OUT
HID-BRIDGE_XT2IN
40 MHz
1000pF
C210

A012 XTAL

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These assemblies are ESD sensitive. ESD precautions shall be observed.

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
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